

Notice of References Cited

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09/736,043

Applicant(s)/Patent Under
Reexamination
KUO, YUE

Examiner
W. David Coleman

Art Unit
2823

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U.S. PATENT DOCUMENTS

*		Document Number Country Code-Number-Kind Code	Date MM-YYYY	Name	Classification
	A	US-6,010,603	01-2000	Ye et al	204/192.35
	B	US-5,350,484	09-1994	Gardner et al.	438/659
	C	US-6,281,589	08-2001	Nguyen et al.	257/758
	D	US-6,057,230	05-2000	Liu, Chi Kang	438/622
	E	US-5,736,002	04-1998	Allen et al.	156/628.1
	F	US-			
	G	US-			
	H	US-			
	I	US-			
	J	US-			
	K	US-			
	L	US-			
	M	US-			

FOREIGN PATENT DOCUMENTS

*		Document Number Country Code-Number-Kind Code	Date MM-YYYY	Country	Name	Classification
	N					
	O					
	P					
	Q					
	R					
	S					
	T					

NON-PATENT DOCUMENTS

*		Include as applicable: Author, Title Date, Publisher, Edition or Volume, Pertinent Pages)
	U	Markert et al., "Mechanism studies of Cu RIE for VLSI interconnections" March 1997, MicroElectronic Engineering, vol. 37/38 pp 127-133
	V	Steinbruchel, "Patterning of copper for multilevel metallization: reactive ion etching and chemical-mechanical polishing", Jan. 1995, Applied Surface Science, vol. 91, pp 139-146.
	W	
	X	

*A copy of this reference is not being furnished with this Office action. (See MPEP § 707.05(a))
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